

## Low drop power Schottky rectifier

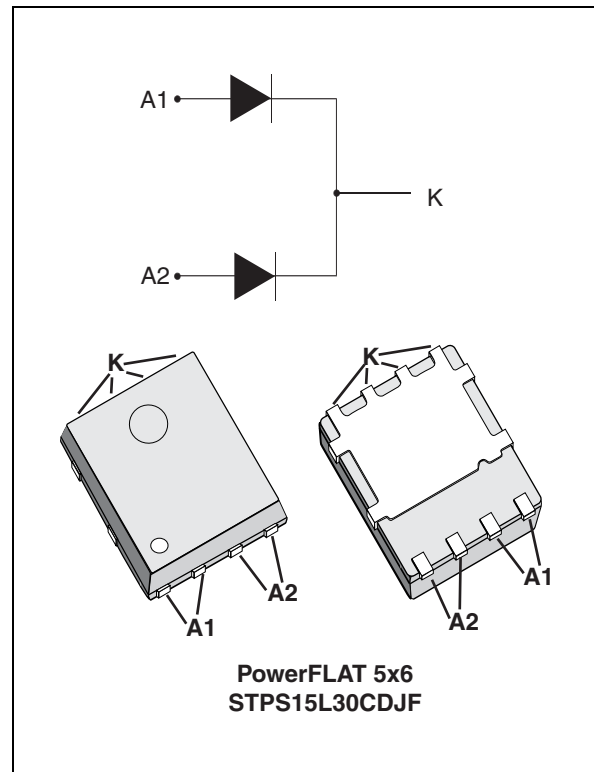
### Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop
- Low thermal resistance
- High avalanche capability specified

### Description

Dual center tap Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Packaged in PowerFLAT™, this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	2 x 7.5 A
$V_{RRM}$	30 V
$T_j$ (max)	150 °C
$V_F$ (typ)	0.34 V

TM: PowerFLAT is a trademark of STMicroelectronics

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, per diode)**

Symbol	Parameter		Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage		30	V	
I <sub>F(RMS)</sub>	Forward rms current		10	A	
I <sub>F(AV)</sub>	Average forward current $\delta = 0.5$	T <sub>c</sub> = 140 °C	Per diode	7.5	A
			Per device	15	
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	75	A	
I <sub>RRM</sub>	Peak repetitive reverse current	t <sub>p</sub> = 2 $\mu$ s square F= 1 kHz	1	A	
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 1 $\mu$ s T <sub>j</sub> = 25 °C	2800	W	
T <sub>stg</sub>	Storage temperature range		-65 to + 175	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>		150	°C	

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case	Per diode	2.5	°C/W
		Total	1.6	
R <sub>th(c)</sub>	Coupling		0.7	

When diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode1}) \times R_{th(j-c)}(\text{per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

**Table 4. Static electrical characteristics (per diode)**

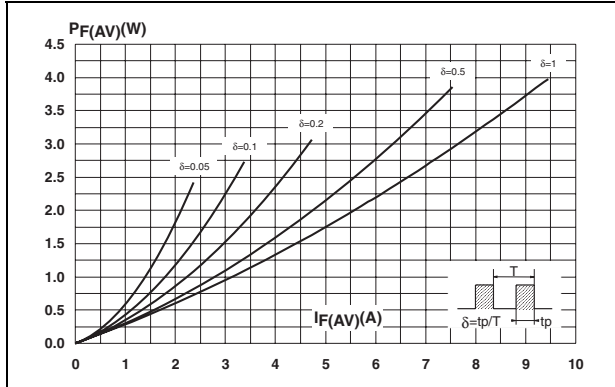
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	-	-	1	mA
		T <sub>j</sub> = 125 °C	-	70	140	
V <sub>F</sub> <sup>(1)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C   I <sub>F</sub> = 7.5 A	-	-	0.48	V
		T <sub>j</sub> = 125 °C   I <sub>F</sub> = 7.5 A	-	0.34	0.39	
		T <sub>j</sub> = 25 °C   I <sub>F</sub> = 15 A	-	-	0.57	
		T <sub>j</sub> = 125 °C   I <sub>F</sub> = 15 A	-	0.44	0.51	

1. Pulse test: t<sub>p</sub> = 380  $\mu$ s,  $\delta < 2\%$

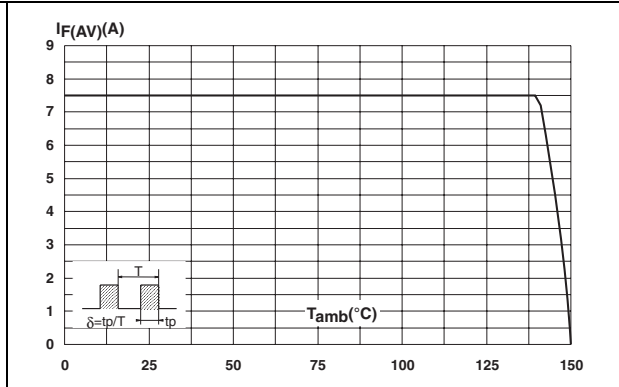
To evaluate the conduction losses use the following equation:

$$P = 0.27 \times I_{F(AV)} + 0.016 I_{F(RMS)}^2$$

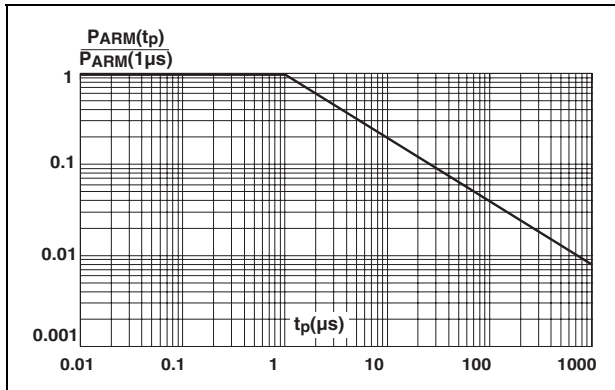
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



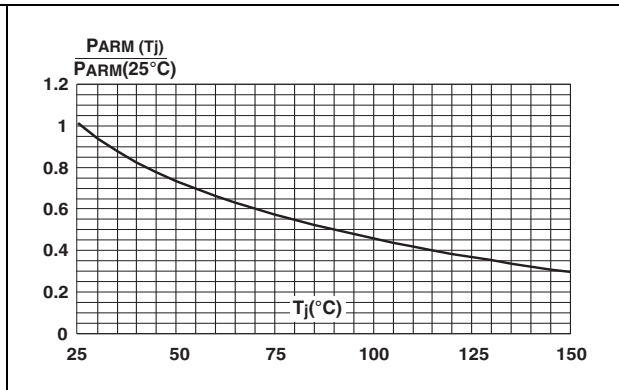
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode)**



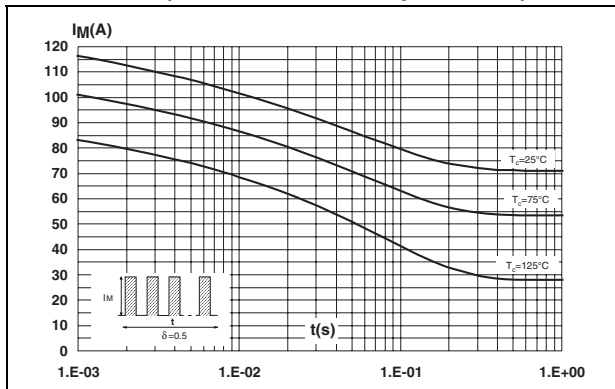
**Figure 3. Normalized avalanche power derating versus pulse duration**



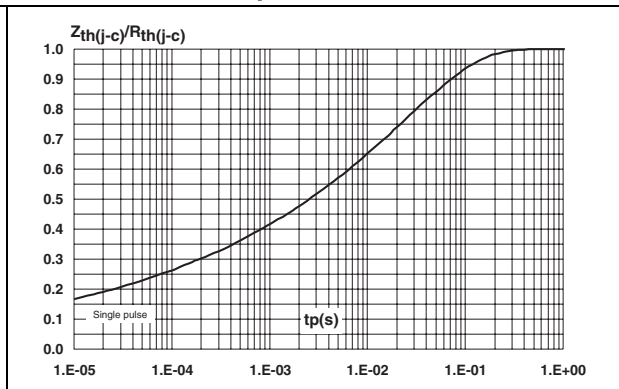
**Figure 4. Normalized avalanche power derating versus junction temperature**



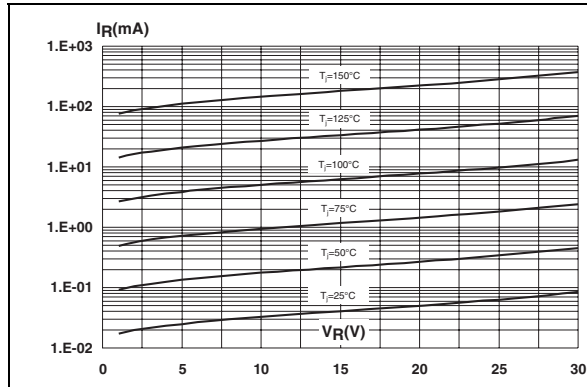
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)**



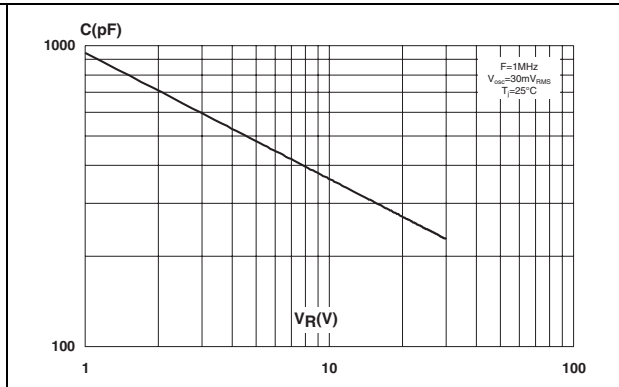
**Figure 6. Relative variation of thermal impedance, junction to case, versus pulse duration**



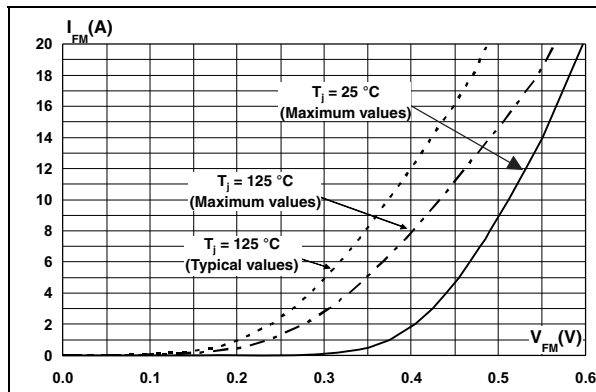
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)**



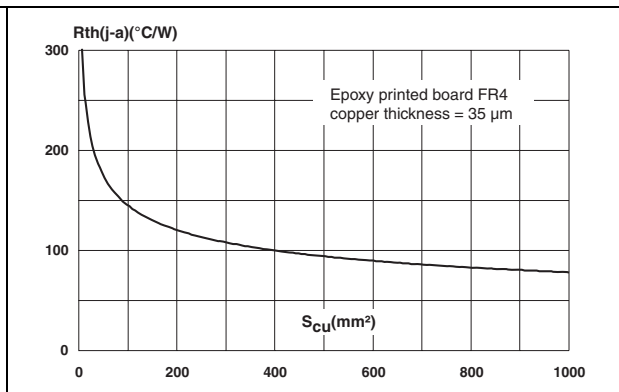
**Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)**



**Figure 9. Forward voltage drop versus forward current (per diode)**



**Figure 10. Thermal resistance junction to ambient versus copper surface under each lead**



## 2 Package information

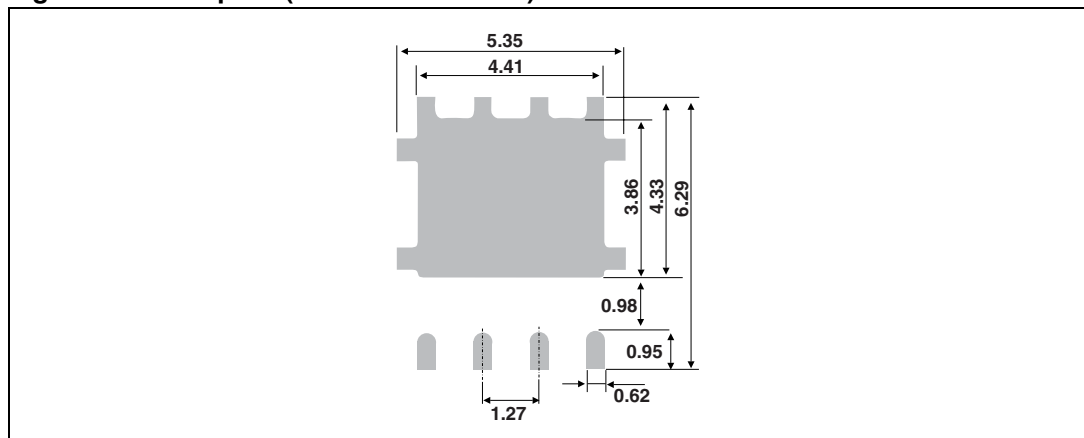
- Epoxy meets UL94,V0
- Lead-free package

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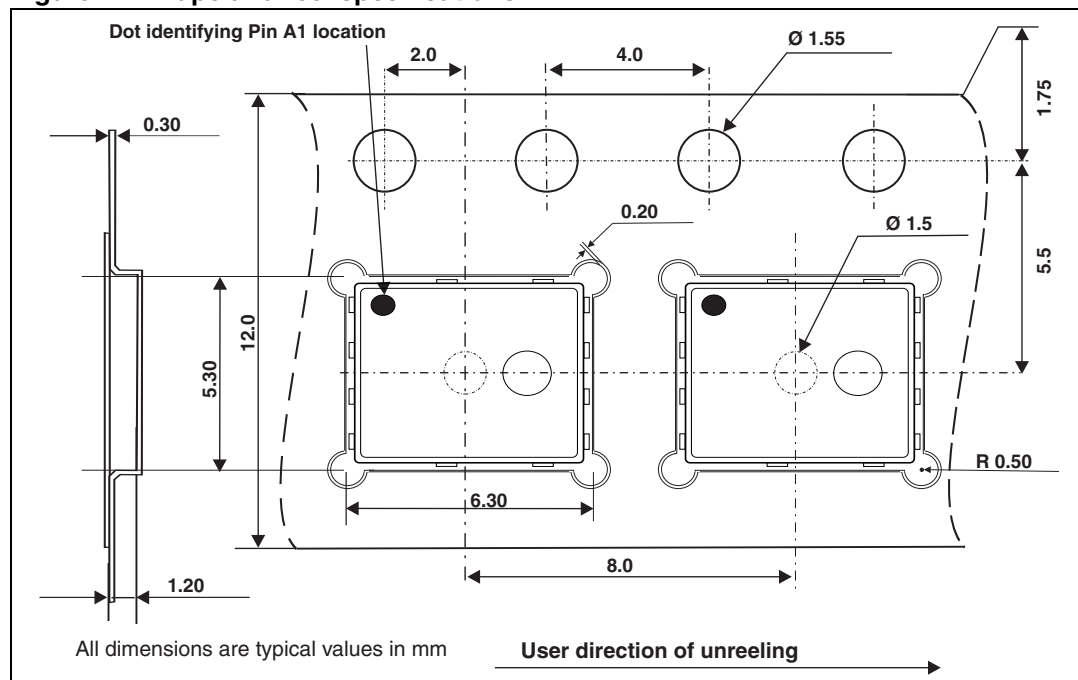
**Table 5. PowerFLAT 5x6 dimensions**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80		1.00	0.031		0.039
A1	0.02		0.05	0.001		0.002
A2		0.25			0.010	
b	0.30		0.50	0.012		0.020
D		5.20			0.205	
D2	4.11		4.31	0.162		0.170
e		1.27			0.050	
E		6.15			0.242	
E2	3.50		3.70	0.138		0.146
L	0.50		0.80	0.020		0.031
K	1.275		1.575	0.050		0.062

**Figure 11. Footprint (dimensions in mm)**



**Figure 12. Tape and reel specifications**



### 3 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS15L30CDJFTR	PS15 L30C	PowerFLAT 5x6	0.095 g	3000	Tape and reel

### 4 Revision history

**Table 7. Document revision history**

Date	Revision	Changes
13-May-2009	1	First issue.
09-Nov-2009	2	Updated <a href="#">Table 1</a> .
30-Jul-2010	3	Replace Power QFN with PowerFLAT. Updated <a href="#">Figure 9</a> .
18-May-2011	4	Added reference E in <a href="#">Table 5</a> . Updated package graphics. Removed dash from order code and updated marking in <a href="#">Table 6</a> . Added <a href="#">Figure 12</a> .

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